

Form PTO-1595 (Rev. 09/04)  
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To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)/Execution Date(s):  
TOKIHIKO SAWASHI

2. Name and address of receiving party(ies)

Name: SONY CORPORATION  
Internal Address: \_\_\_\_\_  
Street Address: 7-35, Kitashinagawa 6-chome  
Shinagawa-Ku  
City: Tokyo  
State: \_\_\_\_\_  
Country: JAPAN Zip: 141-0001  
Additional name(s) & address(es) attached:  Yes  No

Execution Date(s): January 28, 2005  
Additional name(s) of conveying party(ies) attached?  Yes  No

3. Nature of Conveyance:  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Government Interest Assignment  
 Executive Order 9424, Confirmatory License  
 Other \_\_\_\_\_

4. Application or patent number(s):  
A. Patent Application No.(s)  
10/985,120  
Additional numbers attached?  Yes  No


This document is being filed together with a new application.  
B. Patent No.(s)  
 Yes  No

5. Name and address to whom correspondence concerning document should be mailed:  
Name: Robert B. Cohen  
LENER, DAVID, LITTENBERG,  
KRUMHOLZ & MENTLIK, LLP  
Internal Address: Atty. Dkt.:  
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6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00  
 Authorized to be charged by credit card  
 Authorized to be charged to deposit account  
 Enclosed  
 None required (government interest not affecting title)

8. Payment Information  
a. Credit Card Last 4 Numbers \_\_\_\_\_  
Expiration Date \_\_\_\_\_  
b. Deposit Account Number 12-1095  
Authorized User Name Robert B. Cohen

9. Signature:   
Signature  
Robert B. Cohen - 32,768  
Name of Person Signing

February 11, 2005  
Date  
Total number of pages including cover sheet, attachments, and documents: 2

CH \$40.00 121095 10985120

Docket Number: SONYJP 3.0-417  
Sony Ref. No.: S04P1566US00

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in:

**POWER AMPLIFICATION CIRCUITS**

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the application number and filing date of this application in the spaces that follow: Application Number: 10/985,120 Filing Date: November 10, 2004

This assignment executed on the dates indicated below.

<u>Tokihiko Sawashi</u>	
Name of First or Sole Inventor	Execution Date of U.S. Patent Application
<u>Tokyo, Japan</u>	
Residence of First or Sole Inventor	
<u>T. Sawashi</u>	<u>1.28, 2005</u>
Signature of First or Sole Inventor	Date of this Assignment